15th Topical Meeting on Electrical Performance of Electronic Packaging

EPEP 2006

October 23-25, 2006
Scottsdale, Arizona

Sponsors

IEEE Microwave Theory and Techniques Society

The IEEE Components, Packaging and Manufacturing Technology Society

Call for papers (papers due July 10)

The **general subject of the meeting** is the electrical modeling, design, analysis, and characterization of electronic interconnections and packaging structures. Authors are invited to submit papers describing new technical contributions in the areas broadly covered below:

- RF/microwave packaging structures and their electrical performance
- Microwave performance of multilayer LTCC packaging
- MMIC modules and high density packaging
- Experimental characterization techniques EMC/EMI sources & effects
- Prediction/measurement of radiation from on-chip sources, interconnect structures and packages
- Electrical issues in MEMS packaging
- New and innovative interconnect packaging structures and their electrical performance
- Electrical design implications for low cost, high volume packaging
- Signal integrity in mixed signal integrated circuits
- Packaging solutions for one chip radios: design and modeling
- Performance of packaging for automotive radar systems
- Optoelectronic packaging; structure and system applications
- Current and future issues related to on-chip interconnections
- Router friendly models and modeling tools: accuracy & efficiency
- Modeling and design of high speed digital IO circuits: signal propagation and reception
- On-chip power delivery and regulation
- Advances in modeling core switching noise, and design of novel solutions
- On-chip measurement techniques
- Package analysis, including numerical methods
- Electromagnetic analysis tools
- Advances in transmission-line techniques
- Power distribution and package resonance

Conference Co-chairs: Moises Cases, IBM; Paul Franzon, North Carolina State University

Conference Web Page: Detailed information can be found at **www.epep.org**

Paper Submission: Information for authors can be found on the conference web page. Electronic submissions of no more than four pages must be received no later than **July 10, 2006.**

Student Paper Award: Two awards will be presented to the best two papers submitted by students.

Short Courses/Workshops: On Sunday, October 22, 2006, a workshop entitled "Future Directions in Packaging" will be presented and short courses/tutorials will be offered.